

L Number	Hits	Search Text	DB	Time stamp
2	2561	((elimina\$4 reduce\$ decreas\$4 lower\$4) and stress).ti.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 14:42
3	2070	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress).ti.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 14:43
4	1415	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 15:10
5	31	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress).clm.) and cold near4 work\$3	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 14:50
6	9	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress).clm.) and cold near4 work\$3).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 14:51
7	308	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress) and (burnish\$4 polish\$4).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 15:17
8	1	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress and (burnish\$4 polish\$4)and cold).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 15:13
9	34	((elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress) and (burnish\$4 polish\$ and compress\$4).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 15:21
10	1	(cold and(elimina\$4 reduce\$ decreas\$4 lower\$4) near4 stress and (burnish\$4 polish\$) and compress\$4).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/06 15:25
-	81	73/862.043.ccls.	USPAT	2001/03/30 12:30
-	235	73/826\$3.ccls.	USPAT	2001/03/30 12:31
-	79	73/826\$3.ccls. and method	USPAT	2001/04/03 16:14
-	235	73/826.ccls.	USPAT	2001/03/30 13:06
-	599	73/\$7.ccls. and method and tensile near3 stress	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:16
-	14	73/\$7.ccls. and ((method and tensile near3 stress and pressure).clm.)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:29
-	1	73/\$7.ccls. and ((method and tensile near3 stress and pressure).clm.) and cold near2 work\$2	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:19
-	0	73/\$7.ccls. and method and measure and pressure and (tensile near3 stress) and (cold near2 work\$2) and burnish\$3	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:34
-	14	73/\$7.ccls. and method and measure and pressure and (tensile near3 stress) and cold near2 work\$2	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:21
-	9	73/\$7.ccls. and method and measure and pressure and (tensile near3 (stress tension)) and (cold near2 work\$3) and (burnish\$3 rub\$3 polish\$3 smooth\$3)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:27
-	47	73/\$7.ccls. and ((method and tensile near3 stress and pressure) and (reduce lower short).clm.)	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:39

-	0	(method and measure and pressure and (tensile near3 stress) and (cold near2 work\$2) and burnish\$3).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:37
-	1	method and measure and pressure and (tensile near3 stress) and (cold near2 work\$2) and burnish\$3	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:34
-	15	(method and measure and pressure and (tensile near3 stress) and (cold near2 work\$2) and (burnish\$3 rubbing rub smooth smoothing polish polishing))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:43
-	1	(method and measure and (reduce lower decrease) and (tensile near3 stress) and (cold near2 work\$2) and ((burnish\$3 rubbing rub smooth smoothing polish polishing) near3 (device apparatus machine)))	USPAT; EPO; JPO; Derwent; IBM TDB	2001/04/03 16:45